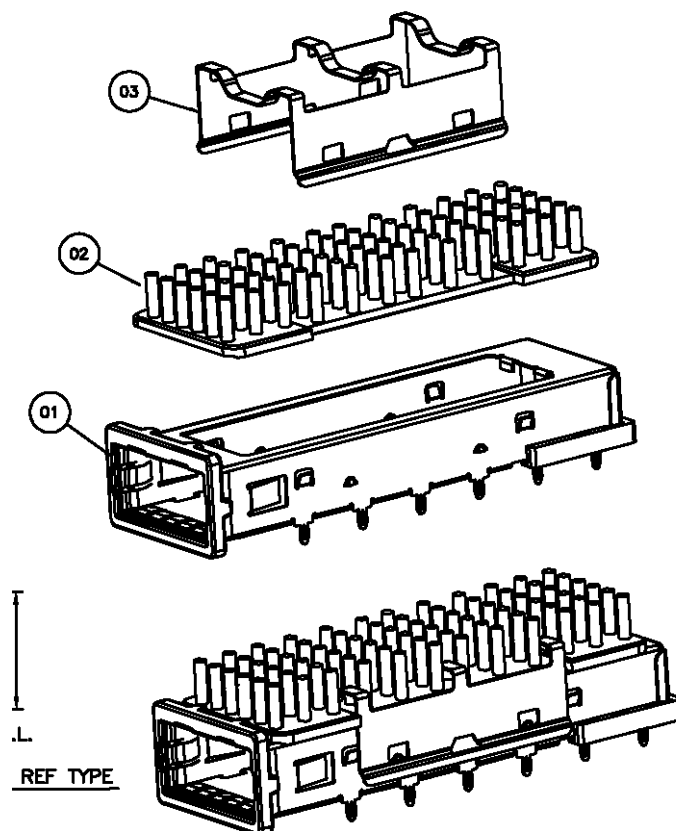


XFP With PCI Heat Sink Kit

XFP-001B

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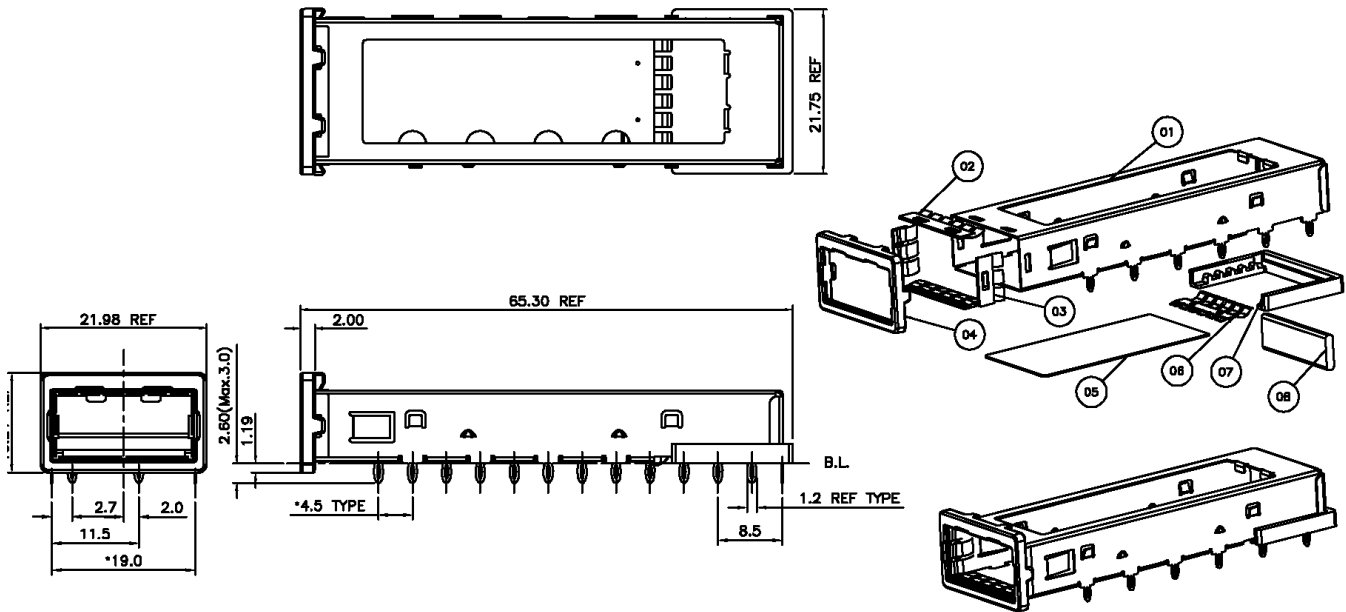
- Design Meets Requirements of XFPMSA Specification Rev. 3.1
- 10 Gigabit Small Form Factor Pluggable Module
- 25um ~ 50 um Copper Underplate
- All materials are RoHS



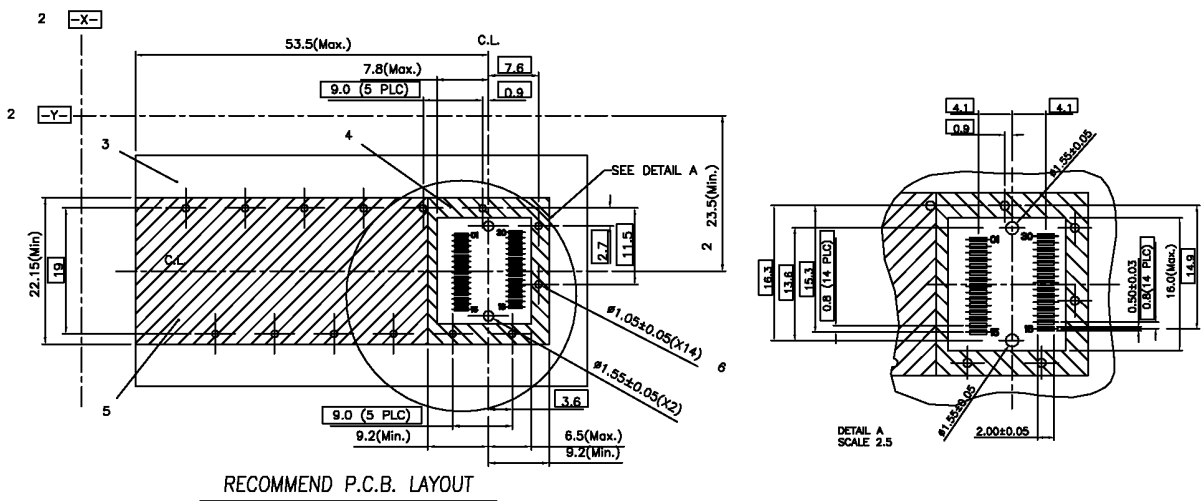
XFP With PCI Heat Sink Kit

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PCB LAYOUT

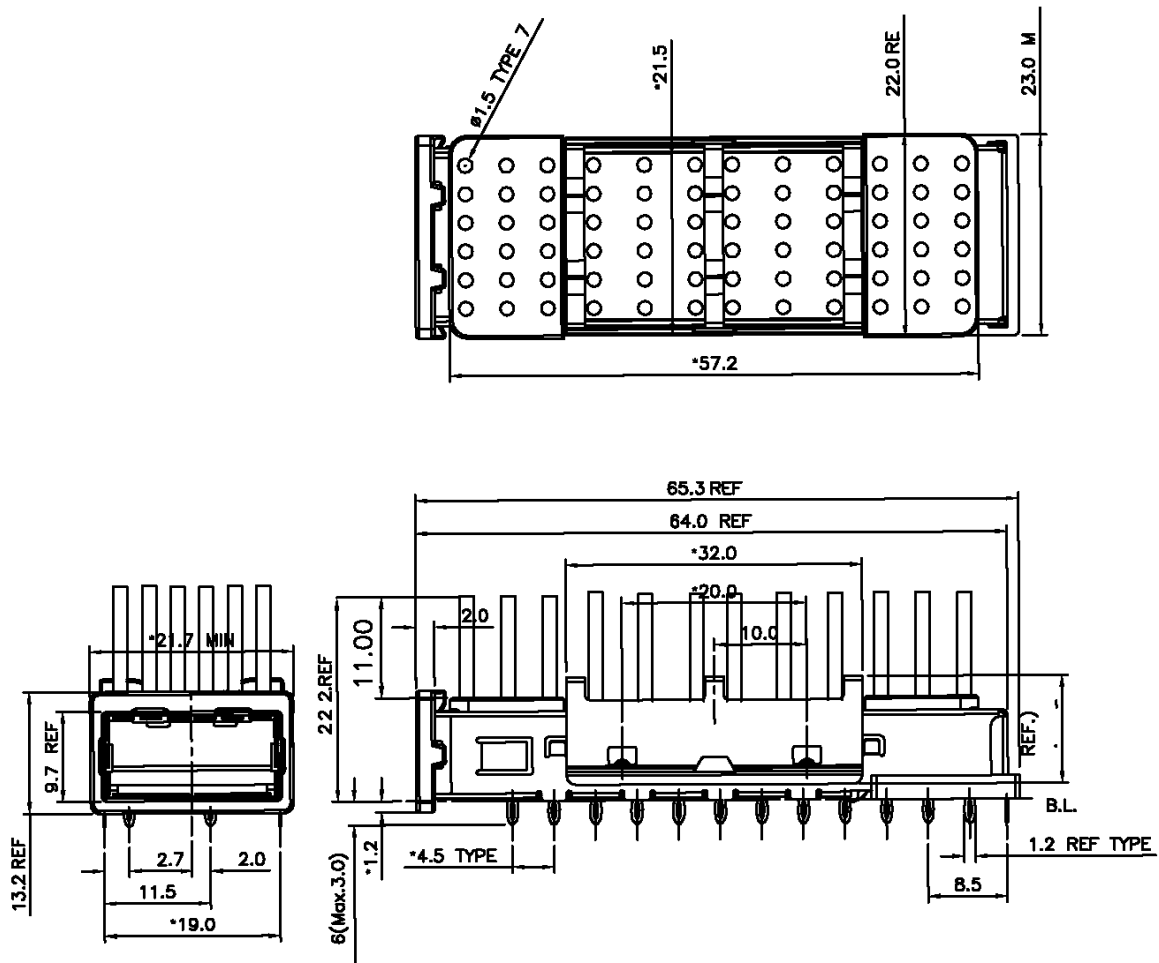


XFP With PCI Heat Sink Kit

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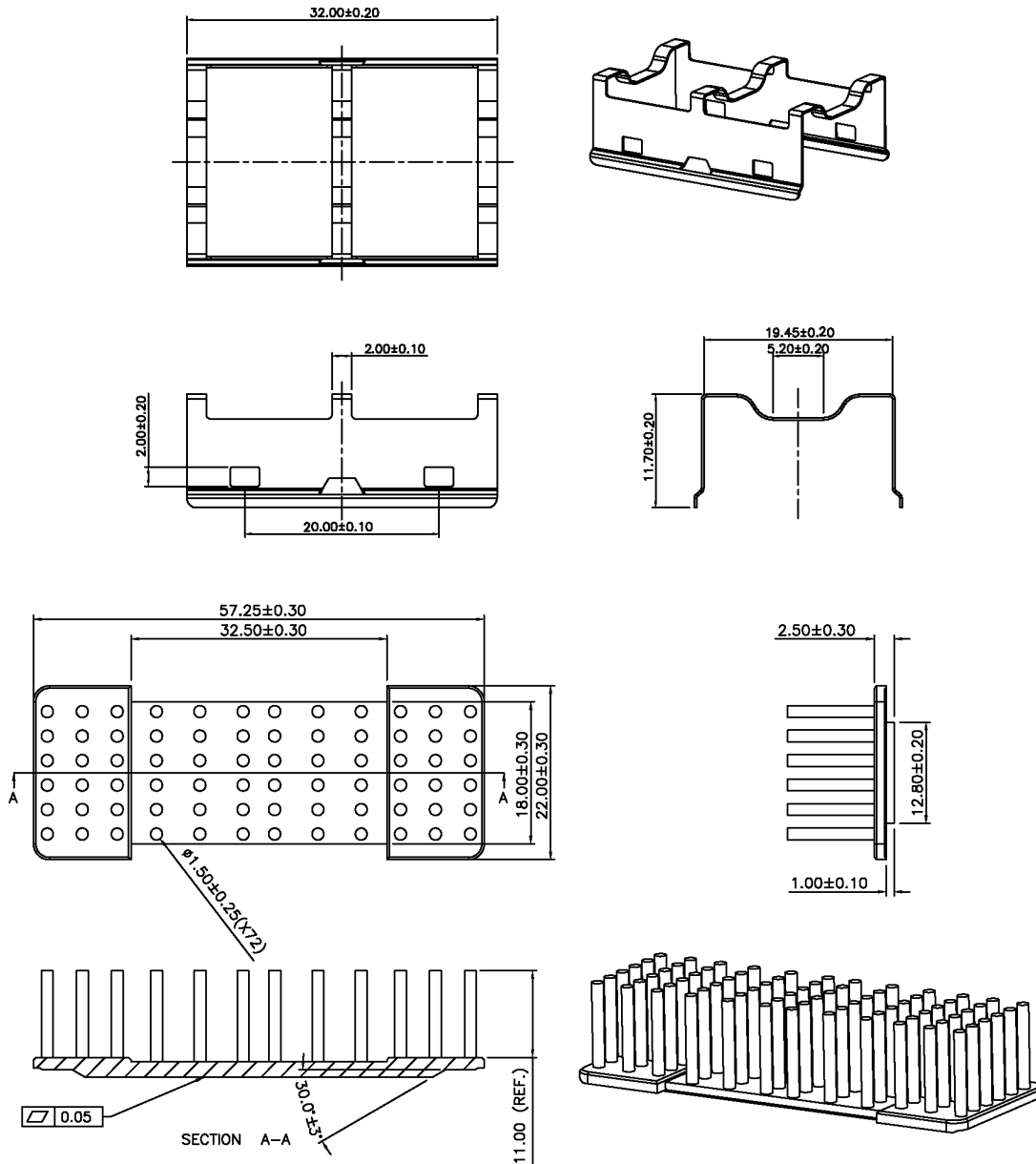
MECHANICAL



XFP With PCI Heat Sink Kit

XFP-001B

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Notes:

1. DATUM X and Y established by customer.
2. DATUM A is top surface of host board.
3. Indicated surfaces to be conductive and connected to chassis ground.
4. Cross-Hatched area denotes component and trace keep-out (except chassis ground)
5. Recommend for P.C.Board Holes – A Hole after drilling 1.15 mm, B Hole: 1.05 mm.
6. Caution – Reflow process will damage cage assembly.